

IGBT

TRENCHSTOP™ IGBT4 Low Power Chip
IGC27T120T8L

Data Sheet

Industrial Power Control

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TRENCHSTOP™ IGBT4 Low Power Chip

Features:

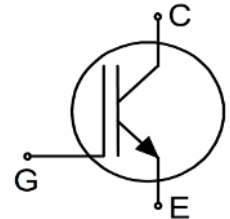
- 1200V trench & field stop technology
- Low switching losses
- Positive temperature coefficient
- Easy paralleling

Recommended for:

- Low / medium power modules

Applications:

- Low / medium power drives



Chip Type	V_{CE}	I_{Cn}^1	Die Size	Package
IGC27T120T8L	1200V	25A	4.99mm x 5.45mm	Sawn on foil

Mechanical Parameters

Die size	4.99 x 5.45		mm ²
Emitter pad size	See chip drawing		
Gate pad size	0.826 x 1.31		
Area total	27.2		
Thickness	115		μm
Wafer size	200		mm
Maximum possible chips per wafer	995		
Passivation frontside	Photoimide		
Pad metal	3200nm AlSiCu		
Backside metal	Ni Ag – system To achieve a reliable solder connection it is strongly recommended not to consume the Ni layer completely during production process		
Die bond	Electrically conductive epoxy glue and soft solder		
Wire bond	Al, ≤500μm		
Reject ink dot size	Ø 0.65mm; max. 1.2mm		
Storage environment	for original and sealed MBB bags	Ambient atmosphere air, temperature 17°C – 25°C, <6 months	
	for open MBB bags	Acc. to IEC62258-3: atmosphere >99% Nitrogen or inert gas, humidity <25%RH, temperature 17°C – 25°C, <6 months	

¹ Nominal collector current at $T_C=100^\circ\text{C}$ for chip packaged in power modules, see application example cited on page 5.

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage, $T_{vj}=25^{\circ}\text{C}$	V_{CE}	1200	V
DC collector current, limited by $T_{vj\text{ max}}^2$	I_C	-	A
Pulsed collector current, t_p limited by $T_{vj\text{ max}}^3$	$I_{C,puls}$	75	A
Gate-emitter voltage	V_{GE}	± 20	V
Operating junction temperature	T_{vj}	-40 ... +175	$^{\circ}\text{C}$
Short circuit data ^{3/4} $V_{GE}=15\text{V}$, $V_{CC}=800\text{V}$, $T_{vj}=150^{\circ}\text{C}$	t_{sc}	10	μs

Static Characteristics (tested on wafer), $T_{vj}=25^{\circ}\text{C}$

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE}=0\text{V}$, $I_C=0.85\text{mA}$	1200	-	-	V
Collector-emitter saturation voltage	V_{CEsat}	$V_{GE}=15\text{V}$, $I_C=25\text{A}$	1.58	1.85	2.07	
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C=0.85\text{mA}$, $V_{GE}=V_{CE}$	5.3	5.8	6.3	
Zero gate voltage collector current	I_{CES}	$V_{CE}=1200\text{V}$, $V_{GE}=0\text{V}$	-	-	2.4	μA
Gate-emitter leakage current	I_{GES}	$V_{CE}=0\text{V}$, $V_{GE}=20\text{V}$	-	-	120	nA
Integrated gate resistor	r_G		none			Ω

Electrical Characteristics ³

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Collector-emitter saturation voltage	V_{CEsat}	$V_{GE}=15\text{V}$, $I_C=25\text{A}$, $T_{vj}=150^{\circ}\text{C}$	-	2.25	-	V
Input capacitance	C_{ies}	$V_{CE}=25\text{V}$, $V_{GE}=0\text{V}$, $f=1\text{MHz}$, $T_{vj}=25^{\circ}\text{C}$	-	1450	-	pF
Reverse transfer capacitance	C_{res}		-	50	-	

² Depending on thermal properties of assembly.

³ Not subject to production test - verified by design/characterization.

⁴ Allowed number of short circuits: <1000; time between short circuits: >1s.



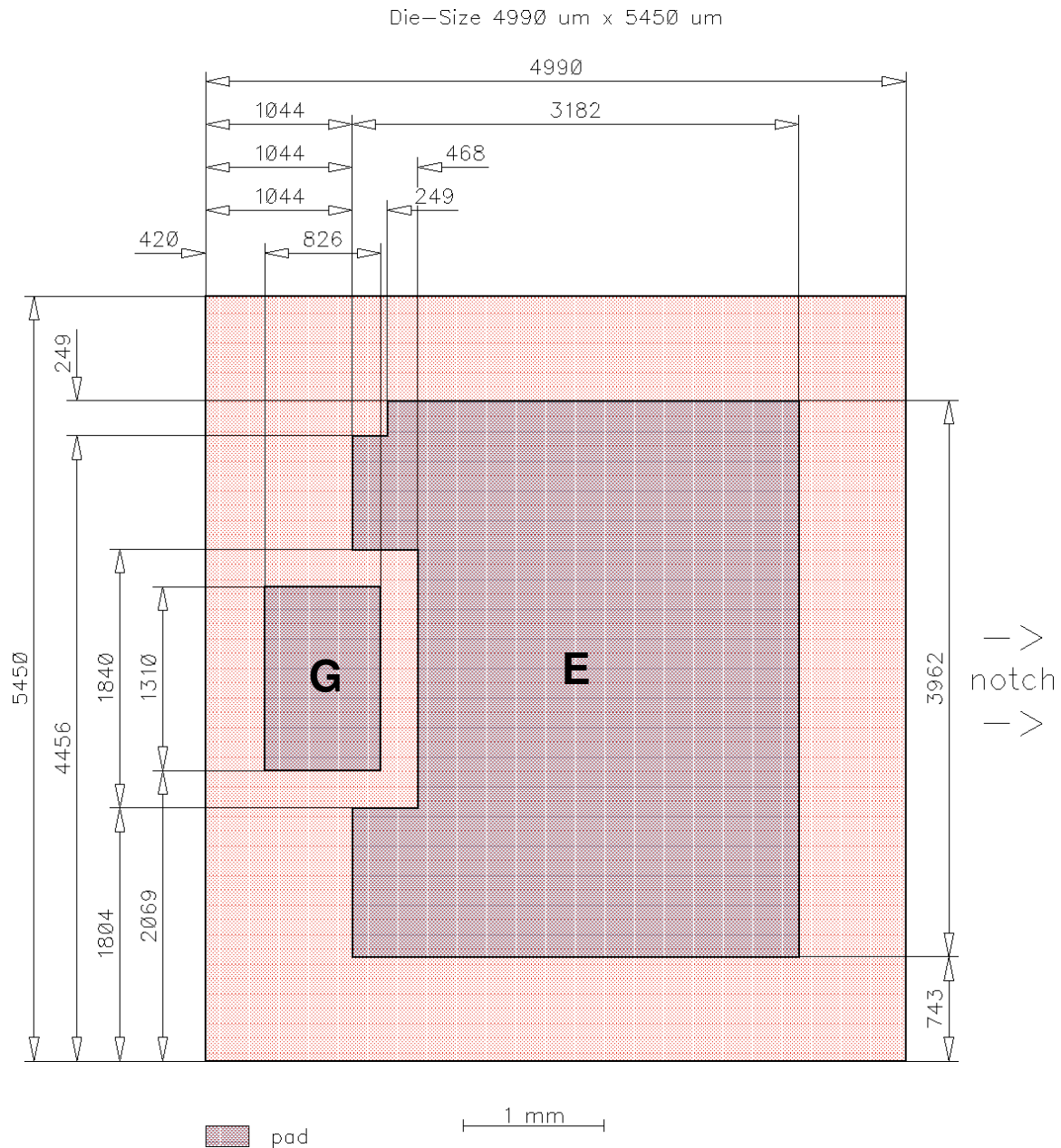
IGC27T120T8L

Further Electrical Characteristics

Switching characteristics and thermal properties are depending strongly on module design and mounting technology and can therefore not be specified for a bare die.

Application example	FP25R12W2T4_B11	Rev. 2.1
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Chip Drawing



E = Emitter

G = Gate



IGC27T120T8L

Bare Die Product Specifics

Test coverage at wafer level cannot cover all application conditions. Therefore it is recommended to test all characteristics which are relevant for the application at package level, including RBSOA and SCSOA.

Description

AQL 0.65 for visual inspection according to failure catalogue

Electrostatic Discharge Sensitive Device according to MIL-STD 883

Revision History

Revision	Subjects (major changes since last revision)	Date
2.0	Final data sheet	18.02.2015
2.1	Update disclaimer	20.08.2015

Relevant Application Notes

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